

Plug and Play, 18-Line SCSI Active Terminator

FEATURES

- Complies with SCSI and SCSI-2 Standards
- 8pF Channel Capacitance during Disconnect
- SCSI Plug and Play, Dual Low Disconnect, Logic Low Command Disconnects All Termination Lines
- Meets SCSI Hot Plugging Capability
- –650mA Sourcing Current for Termination
- +200mA Sinking Current for Active Negation
- 200μA Supply Current in Disconnect Mode
- Trimmed Termination Current to 7%
- Trimmed Impedance to 7%
- Provides Active Termination for 18 Lines

DESCRIPTION

The UC5607 provides 18 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable segment.

The UC5607 provides a low disconnect feature which will disconnect all terminating resistors, and will disable the regulator, greatly reducing standby power. The output channels remain high impedance even without Termpwr applied.

The UC5607 terminator is specially designed with two disconnect pins for full SCSI Plug and Play (PnP) applications.

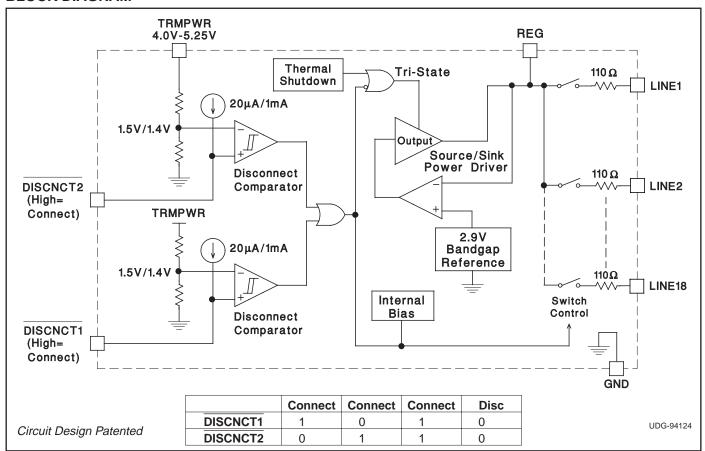
Custom power packages are utilized to allow normal operation at full power conditions (2 Watts).

Internal circuit trimming is utilized, first to trim the impedance to a 7% tolerance, and then most importantly, to trim the output current to a 7% tolerance, as close to the max SCSI spec as possible, which maximizes noise margin in fast SCSI operation.

Other features include thermal shutdown and current limit.

This device is offered in low thermal resistance versions of the industry standard 28 pin wide body SOIC, and 28 pin PLCC, as well as 24 pin DIP.

BLOCK DIAGRAM



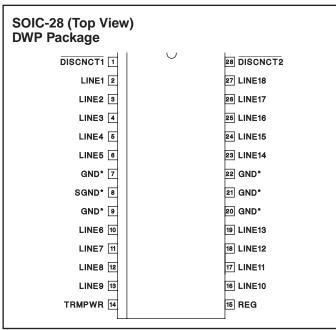
ABSOLUTE MAXIMUM RATINGS

Termpwr Voltage +7V
Signal Line Voltage
Regulator Output Current
Storage Temperature65°C to +150°C
Operating Temperature55°C to +150°C
Lead Temperature (Soldering, 10 Sec.) +300°C

Unless otherwise specified all voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Unitrode Integrated Circuits databook for thermal limitations and considerations of packages.

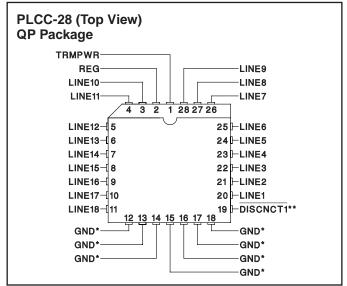
RECOMMENDED OPERATING CONDITIONS

Termpwr Voltage		3.8V to 5.25V
Signal Line Voltage		0V to +5V
Disconnect Input Voltage	0	V to Termpwr



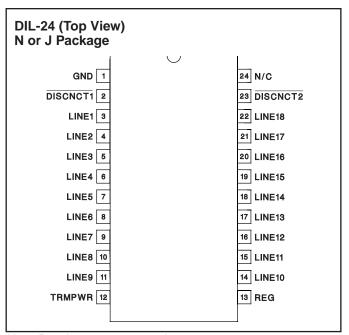
* DWP package pin 8 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.

CONNECTION DIAGRAMS



* QP package pins 12 - 18 serve as both heatsink and signal ground.

^{**} DISCNCT2 is internally tied to ground.



Note: Drawings are not to scale.

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $T_A = 0$ °C to 70°C.

TRMPWR = 4.75V, DISCNCT1 = DISCNCT2 = 2.2V. T_A = T_J. **TEST CONDITIONS** UNIT **PARAMETER** MIN **TYP** MAX S **Supply Current Section** Termpwr Supply Current All termination lines = Open 30 45 mΑ All termination lines = 0.5V 420 470 mΑ Power Down Mode DISCNCT1 = DISCNCT2 = 0V 300 500 μΑ **Output Section (Terminator Lines)** $T_J = 25^{\circ}C$ Terminator Impedance $\Delta I_{LINE} = -5mA$ to -15mA102 110 118 Ohms $0^{\circ}C < T_{.1} < 70^{\circ}C$ 97 110 129 Ohms Output High Voltage V_{TRMPWR} = 4V (Note 1) $T_J = 25^{\circ}C$ 2.6 2.9 3.1 V $0^{\circ}C < T_J < 70^{\circ}C$ 2.55 2.9 3.2 V Max Output Current $V_{LINE} = 0.5V$ $T_J = 25^{\circ}C$ -19.5 -21.9 -22.4mΑ -21.9 $0^{\circ}C < T_{.l} < 70^{\circ}C$ -18.5-22.4mΑ $T_J = 25^{\circ}C$ -21.9 -22.4Max Output Current $V_{LINE} = 0.5V$, TRMPWR = 4V (Note 1) -18.0mΑ $0^{\circ}C < T_J < 70^{\circ}C$ -17.0-21.9-22.4mA DISCNCT1 = DISCNCT2 = 0V, TRMPWR = 0V to 5.25V Output Leakage 10 400 nΑ DISCNCT1 = DISCNCT2 = 0V (Note 2) **Output Capacitance** 8 10 pF **Regulator Section** Regulator Output Voltage All Termination Lines = 5V $T_J = 25^{\circ}C$ 2.7 2.9 V 3.1 $0^{\circ}C < T_{J} < 70^{\circ}C$ ٧ 2.55 2.9 3.2 TRMPWR = 4V to 6V Line Regulation 10 20 mV $I_{REG} = +100$ mA to -100mA Load Regulation 20 50 mV

Note 1: Measuring each termination line while other 17 are low (0.5V).

Note 2: Guaranteed by design. Not 100% tested in production.

APPLICATION INFORMATION

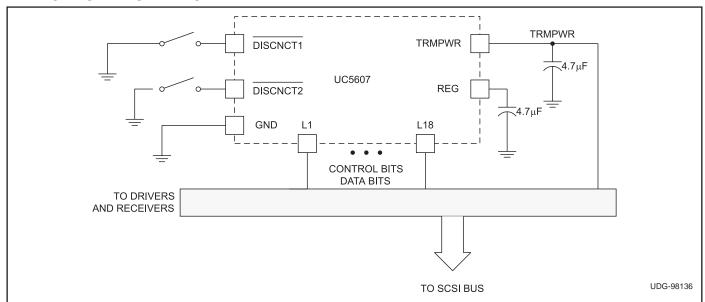


Figure 1: Typical SCSI Bus Configuration Utilizing UC5607 Device

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